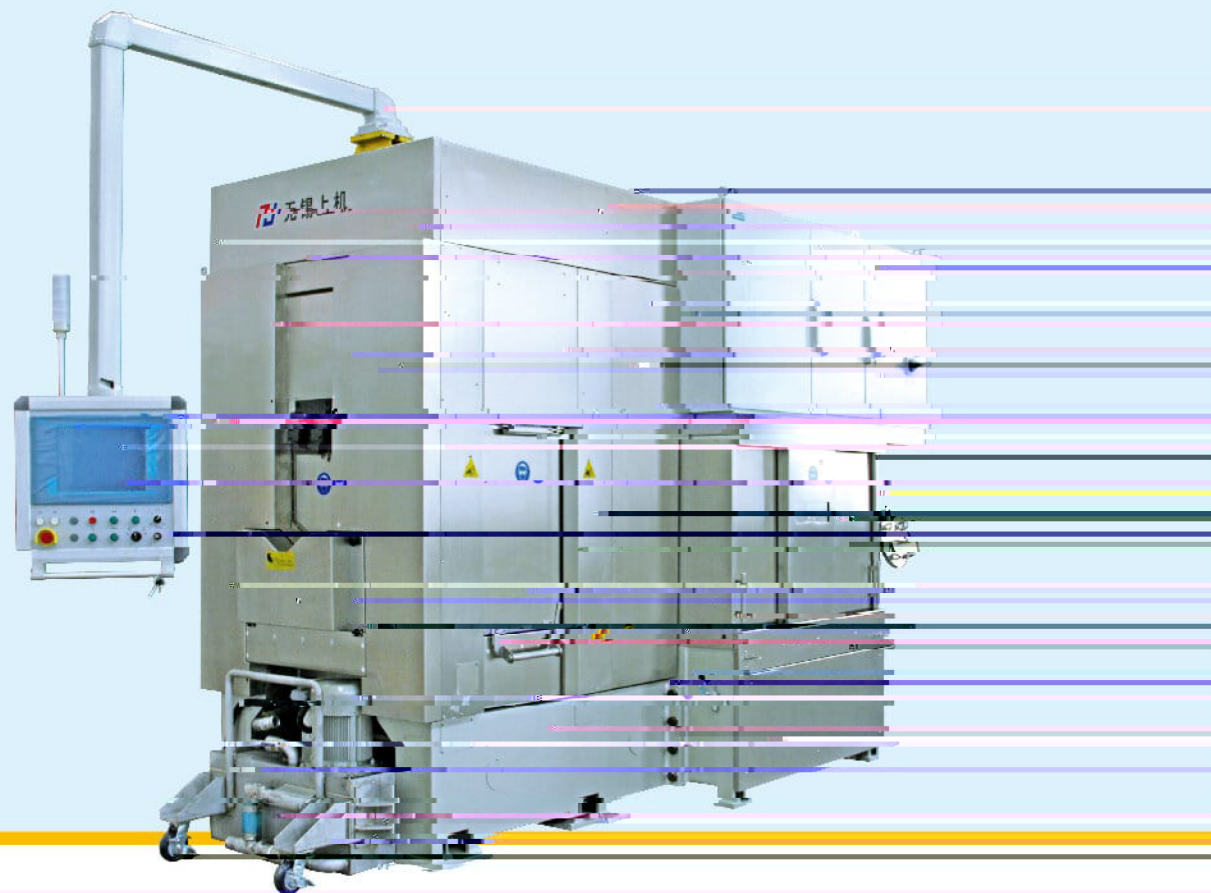


WSK060

蓝宝石切片机

WSK060 Sapphire Slicing Machine



技术规格参数 Specifications and Technical Parameters

规格 Specification	inches (max)
长度 Length	800mm
厚度 Thickness	>0.2mm

主要参数 MAIN PARAMETERS

导轮直径 Guide wheel diameter	220mm
导轮轴距 Guide wheelbase	440mm
导轮长度 Guide wheel length	300mm
线速度 Line speed	30m/s (max)
进给速度 Feed rate	0.05mm, 0.1mm, 0.2mm/min
摇摆角度 Swinging angle	±12°
切割方向 Cutting direction	forward or reverse-cutting and rotary cutting
存储线匣 storage wire heads	>200m
水箱容量 water tank capacity	≈200L

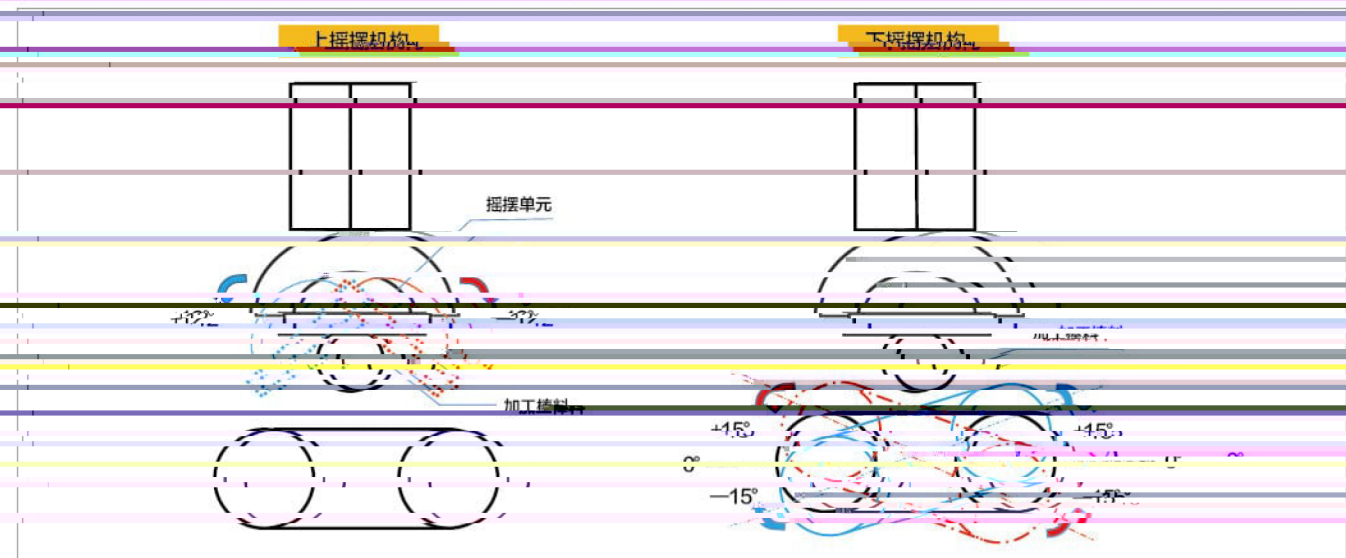
能源供给 power supply

电源电压 Power voltage	220/380V, 50Hz, 50A
平均功率 Average power	35kW
冷却水源 Cooling water	10~15°C

外形尺寸 outline size

机床外形尺寸 (长×宽×高) Equipment size (L×W×H)	4600×2500×3200mm
机床重量 weight	≈ 12000kg

示意图 sketch



设备用途与性能特征

- 本机床用于自动切割长条、坚硬、易脆材料，使用金刚石工具切割硅、锗、石英玻璃、陶瓷、蓝宝石晶体等。
- 机床所有电器元件均采用国际国内知名品牌，保证机床的稳定性。
- 采用西门子控制技术的机电一体化，15"触摸屏。
- 电控柜配备独立温控系统，保证各控制元件正常工作。
- 设备具备摇摆功能，双支撑摇摆单元优化了金刚石线切割蓝宝石的性能，缩短了切割时间，并提高了晶片的质量。
- 滑轮数量最少化设计（仅6个滑轮），减少刚线扭曲和疲劳。

Applications and Features

- This machine is used for automatically cutting long, hard, brittle materials, using diamond tools to cut silicon, germanium, quartz glass, ceramics, sapphire crystals, etc.
- All electrical components apply international and domestic outstanding brands to ensure the stability of the machine.
- Apply integrated PC or SIEMENS simotion controlling system, 15" touch screen
- The electric control cabinet is equipped with independent temperature control system to ensure the normal operation of each control component.
- The equipment features swinging function, and the dual support swinging function unit optimizes the performance of diamond wire-cut sapphire, shortens the cutting time, and improves the quality of the chip.
- Minimal design number of pulleys (only 6 pulleys) to reduce the wire distortion and fatigue.